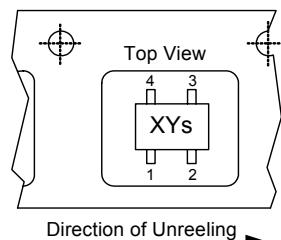
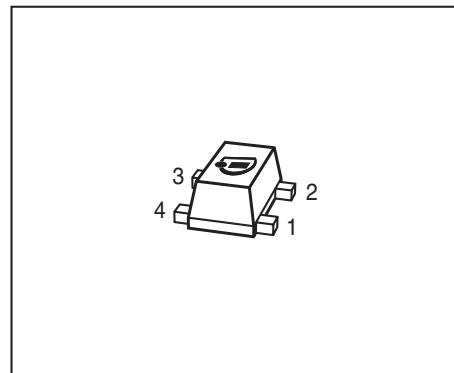


## Low Noise SiGe:C Bipolar RF Transistor

- High gain low noise RF transistor
- Based on Infineon's reliable high volume Silicon Germanium technology
- Outstanding noise figure  $NF_{min} = 0.7$  dB at 1.8 GHz  
Outstanding noise figure  $NF_{min} = 1.3$  dB at 6 GHz
- Maximum stable gain  
 $G_{ms} = 21$  dB at 1.8 GHz  
 $G_{ma} = 10$  dB at 6 GHz
- Pb-free (RoHS compliant) and halogen-free thin small flat package (1.4 x 0.8 x 0.59 mm) with visible leads
- Qualification report according to AEC-Q101 available



**ESD (Electrostatic discharge) sensitive device, observe handling precaution!**

| Type    | Marking | Pin Configuration |     |     |     |   |   | Package |
|---------|---------|-------------------|-----|-----|-----|---|---|---------|
| BFP620F | R2s     | 1=B               | 2=E | 3=C | 4=E | - | - | TSFP-4  |

**Maximum Ratings at  $T_A = 25$  °C, unless otherwise specified**

| Parameter   | Symbol    | Value       | Unit |
|---|-----------|-------------|------|
| Collector-emitter voltage<br>$T_A = 25$ °C                | $V_{CEO}$ | 2.3         | V    |
| $T_A = -55$ °C  |           | 2.1         |      |
| Collector-emitter voltage                                 | $V_{CES}$ | 7.5         |      |
| Collector-base voltage                                    | $V_{CBO}$ | 7.5         |      |
| Emitter-base voltage                                      | $V_{EBO}$ | 1.2         |      |
| Collector current   | $I_C$     | 80          | mA   |
| Base current  | $I_B$     | 3           |      |
| Total power dissipation <sup>1)</sup><br>$T_S \leq 96$ °C | $P_{tot}$ | 185         | mW   |
| Junction temperature                                      | $T_J$     | 150         | °C   |
| Storage temperature                                       | $T_{Stg}$ | -55 ... 150 |      |

<sup>1</sup> $T_S$  is measured on the emitter lead at the soldering point to the pcb

**Thermal Resistance**

| Parameter                                | Symbol     | Value | Unit |
|--|------------|-------|------|
| Junction - soldering point <sup>1)</sup> | $R_{thJS}$ | 290   | K/W  |

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

| Parameter | Symbol | Values |      |      | Unit |
|-----------|--------|--------|------|------|------|
|           |        | min.   | typ. | max. |      |

**DC Characteristics**

|   |                             |     |     |     |               |
|---|-----------------------------|-----|-----|-----|---------------|
| Collector-emitter breakdown voltage<br>$I_C = 1 \text{ mA}, I_B = 0$                    | $V_{(\text{BR})\text{CEO}}$ | 2.3 | 2.8 | -   | V             |
| Collector-emitter cutoff current<br>$V_{CE} = 7.5 \text{ V}, V_{BE} = 0$                | $I_{CES}$                   | -   | -   | 10  | $\mu\text{A}$ |
| Collector-base cutoff current<br>$V_{CB} = 5 \text{ V}, I_E = 0$                        | $I_{CBO}$                   | -   | -   | 100 | nA            |
| Emitter-base cutoff current<br>$V_{EB} = 0.5 \text{ V}, I_C = 0$                        | $I_{EBO}$                   | -   | -   | 3   | $\mu\text{A}$ |
| DC current gain<br>$I_C = 50 \text{ mA}, V_{CE} = 1.5 \text{ V}, \text{pulse measured}$ | $h_{FE}$                    | 110 | 180 | 270 | -             |

<sup>1)</sup>For the definition of  $R_{thJS}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

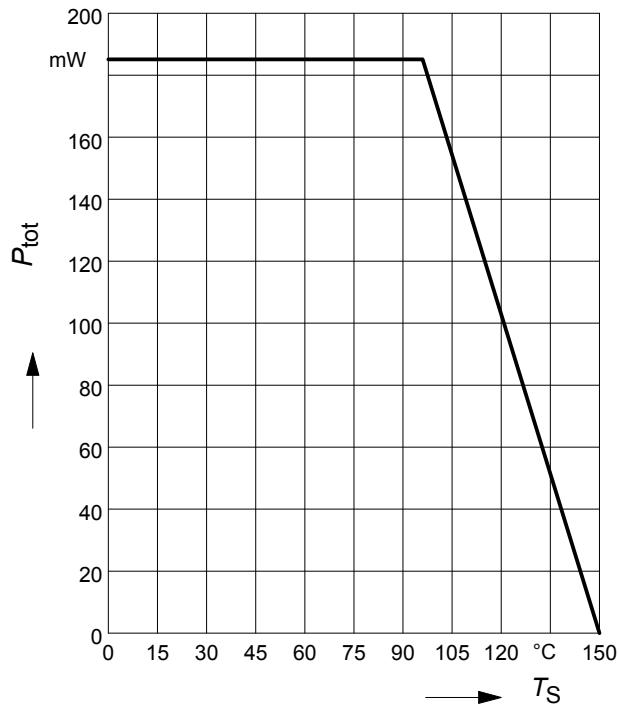
**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

| Parameter  | Symbol        | Values |      |      | Unit |
|--|---------------|--------|------|------|------|
|  |               | min.   | typ. | max. |      |
| <b>AC Characteristics</b> (verified by random sampling)  |               |        |      |      |      |
| Transition frequency<br>$I_C = 50 \text{ mA}, V_{CE} = 1.5 \text{ V}, f = 1 \text{ GHz}$   | $f_T$         | -      | 65   | -    | GHz  |
| Collector-base capacitance<br>$V_{CB} = 2 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0 \text{ V}$ ,<br>emitter grounded  | $C_{cb}$      | -      | 0.12 | 0.2  | pF   |
| Collector emitter capacitance<br>$V_{CE} = 2 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0 \text{ V}$ ,<br>base grounded  | $C_{ce}$      | -      | 0.2  | -    |      |
| Emitter-base capacitance<br>$V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{CB} = 0 \text{ V}$ ,<br>collector grounded  | $C_{eb}$      | -      | 0.45 | -    |      |
| Minimum noise figure<br>$I_C = 5 \text{ mA}, V_{CE} = 1.5 \text{ V}, f = 1.8 \text{ GHz}, Z_S = Z_{Sopt}$<br>$I_C = 5 \text{ mA}, V_{CE} = 1.5 \text{ V}, f = 6 \text{ GHz}, Z_S = Z_{Sopt}$ | $NF_{min}$    | -      | 0.7  | -    | dB   |
| -  |               | -      | 1.3  | -    |      |
| Power gain, maximum stable <sup>1)</sup><br>$I_C = 50 \text{ mA}, V_{CE} = 1.5 \text{ V}, Z_S = Z_{Sopt}$ ,<br>$Z_L = Z_{Lopt}, f = 1.8 \text{ GHz}$   | $G_{ms}$      | -      | 21   | -    | dB   |
| Power gain, maximum available <sup>1)</sup><br>$I_C = 50 \text{ mA}, V_{CE} = 1.5 \text{ V}, Z_S = Z_{Sopt}$ ,<br>$Z_L = Z_{Lopt}, f = 6 \text{ GHz}$  | $G_{ma}$      | -      | 10   | -    | dB   |
| Transducer gain<br>$I_C = 50 \text{ mA}, V_{CE} = 1.5 \text{ V}, Z_S = Z_L = 50 \Omega$ ,<br>$f = 1.8 \text{ GHz}$<br>$f = 6 \text{ GHz}$  | $ S_{21e} ^2$ | -      | 19.5 | -    | dB   |
| -  |               | -      | 9.5  | -    |      |
| Third order intercept point at output <sup>2)</sup><br>$V_{CE} = 2 \text{ V}, I_C = 50 \text{ mA}, Z_S = Z_L = 50 \Omega, f = 1.8 \text{ GHz}$   | $IP3$         | -      | 25   | -    | dBm  |
| 1dB compression point at output<br>$I_C = 50 \text{ mA}, V_{CE} = 2 \text{ V}, Z_S = Z_L = 50 \Omega, f = 1.8 \text{ GHz}$   | $P_{-1dB}$    | -      | 14   | -    |      |

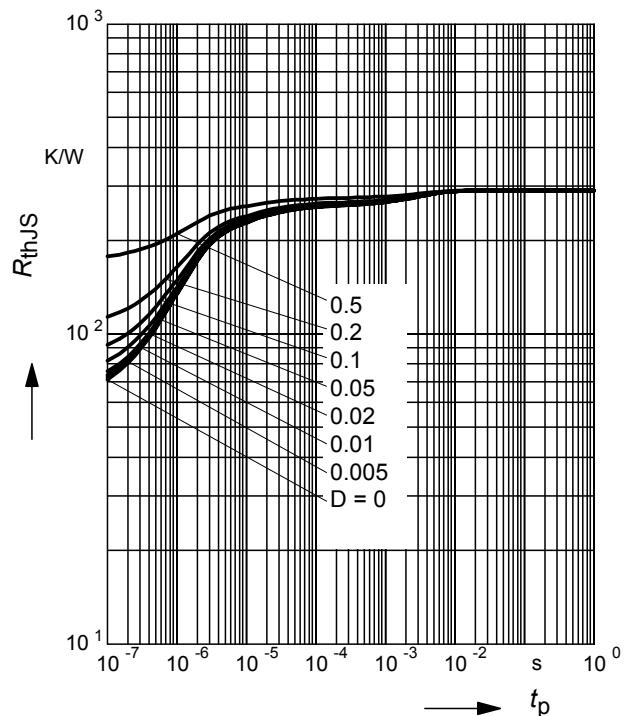
<sup>1</sup> $G_{ma} = |S_{21e}| / S_{12e} \quad (k - (k^2 - 1)^{1/2})$ ,  $G_{ms} = |S_{21e}| / S_{12e}|$ 
<sup>2</sup>IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is  $50\Omega$  from 0.1 MHz to 6 GHz

**Total power dissipation  $P_{\text{tot}} = f(T_S)$**

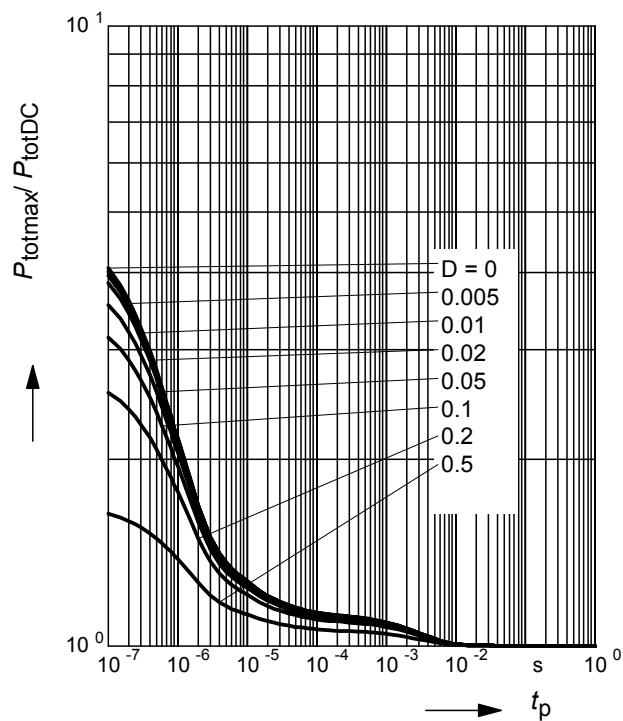


**Permissible Pulse Load  $R_{\text{thJS}} = f(t_p)$**



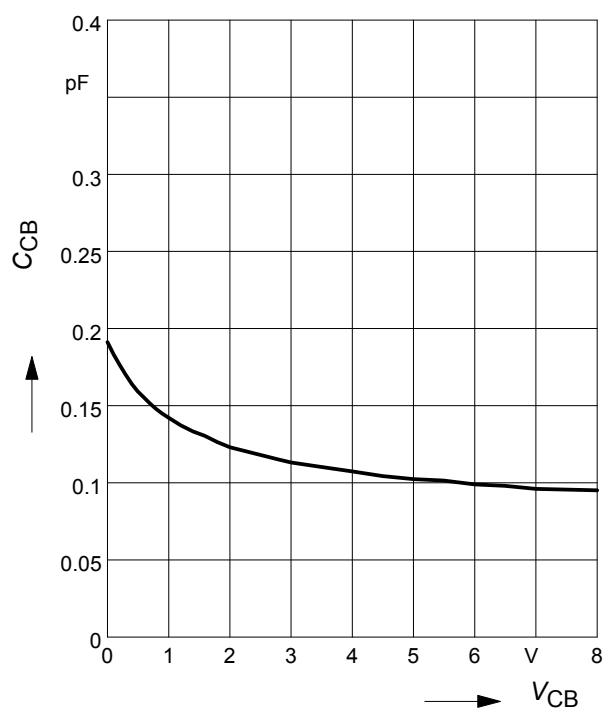
**Permissible Pulse Load**

$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$



**Collector-base capacitance  $C_{\text{cb}} = f(V_{\text{CB}})$**

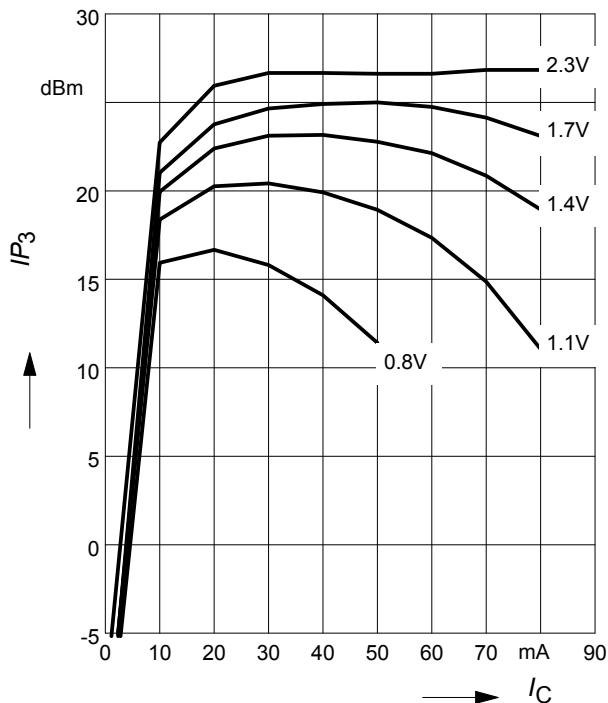
$f = 1\text{MHz}$



**Third order Intercept Point  $IP_3 = f(I_C)$** 

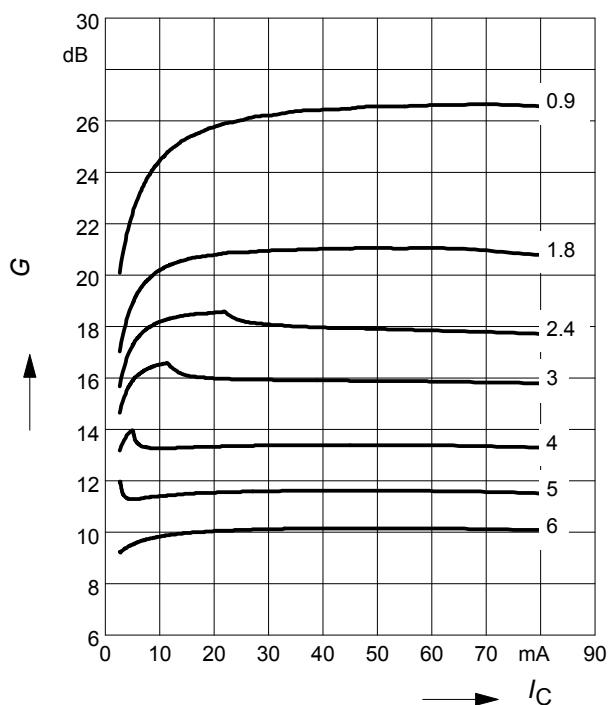
(Output,  $Z_S = Z_L = 50\Omega$ )

$V_{CE}$  = parameter,  $f = 1.8\text{GHz}$


**Power gain  $G_{ma}, G_{ms} = f(I_C)$** 

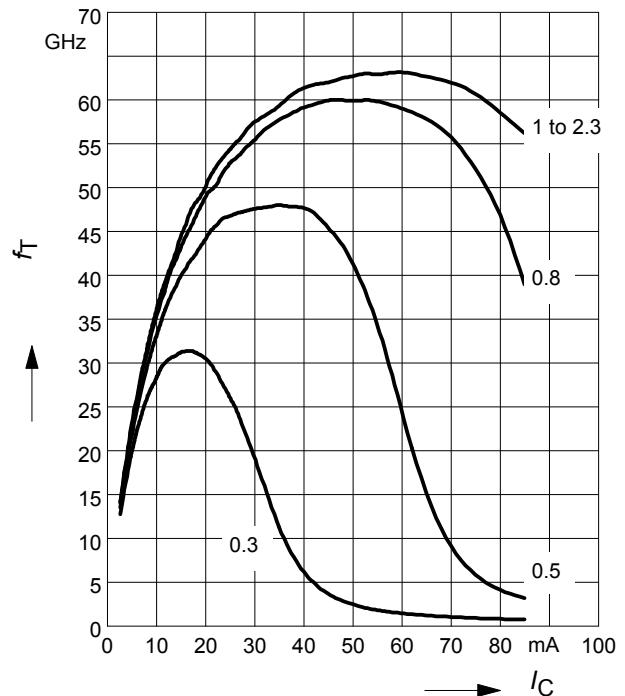
$V_{CE} = 1.5\text{V}$

$f$  = Parameter in GHz


**Transition frequency  $f_T = f(I_C)$** 

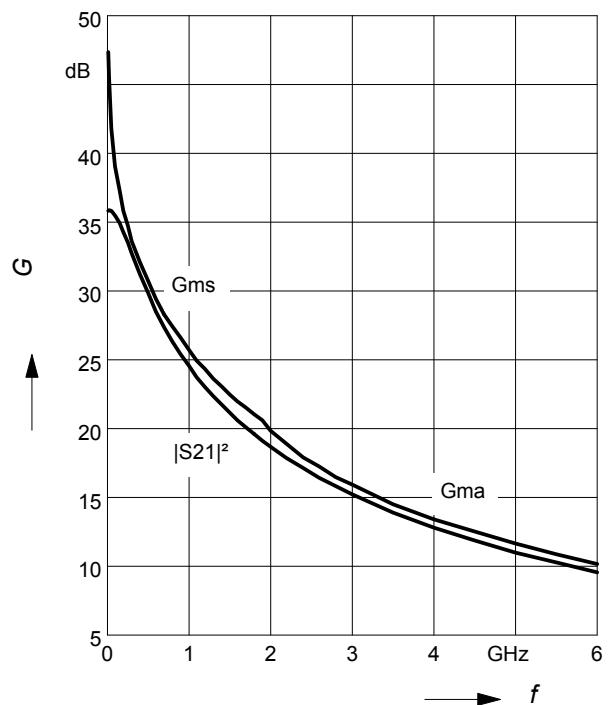
$f = 1\text{GHz}$

$V_{CE}$  = Parameter in V


**Power Gain  $G_{ma}, G_{ms} = f(f)$ ,**

$|S_{21}|^2 = f(f)$

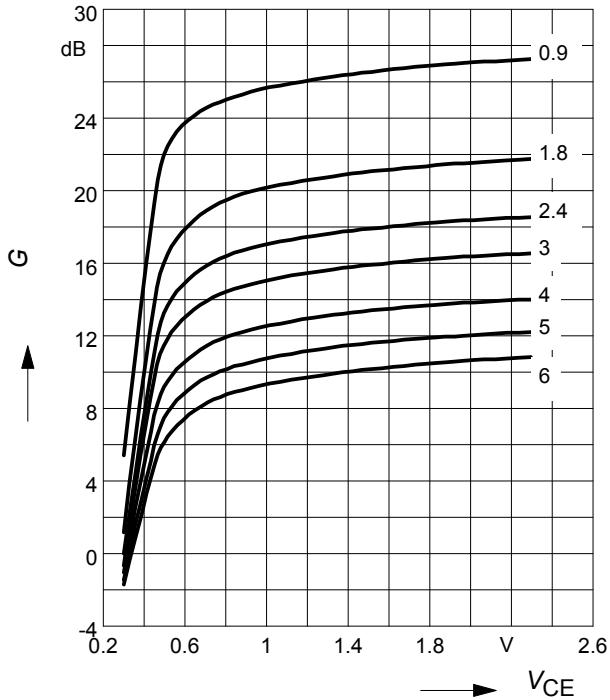
$V_{CE} = 1.5\text{V}, I_C = 50\text{mA}$



**Power gain  $G_{\text{ma}}, G_{\text{ms}} = f(V_{\text{CE}})$**

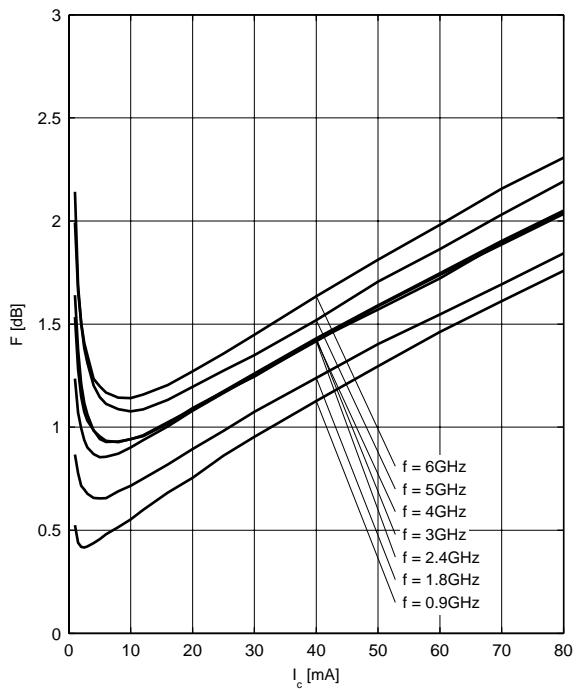
$I_{\text{C}} = 50\text{mA}$

$f = \text{Parameter in GHz}$



**Noise figure  $F = f(I_{\text{C}})$**

$V_{\text{CE}} = 1.5\text{V}, Z_{\text{S}} = Z_{\text{Sopt}}$

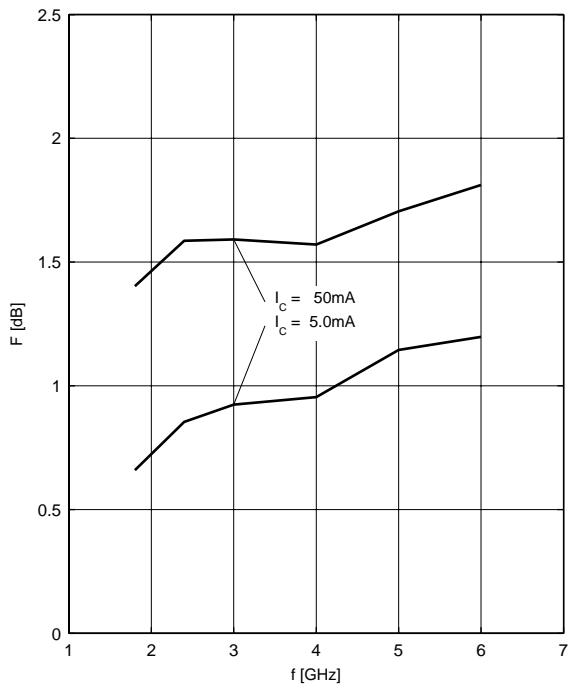
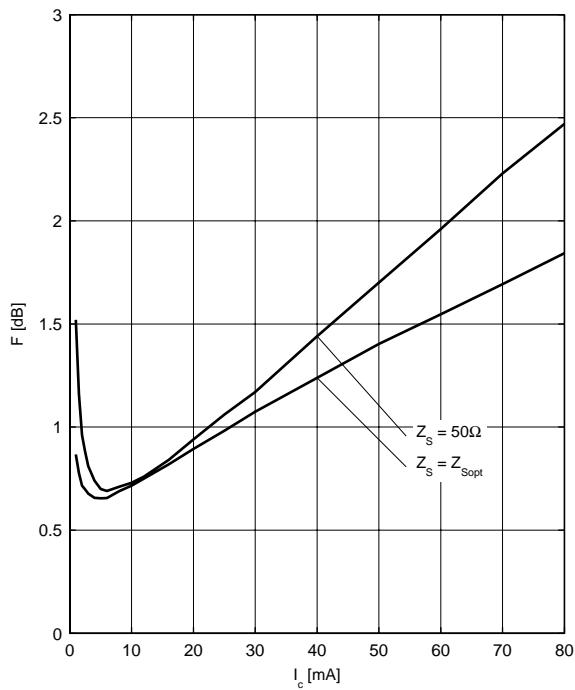


**Noise figure  $F = f(I_{\text{C}})$**

$V_{\text{CE}} = 1.5\text{V}, f = 1.8\text{ GHz}$

**Noise figure  $F = f(f)$**

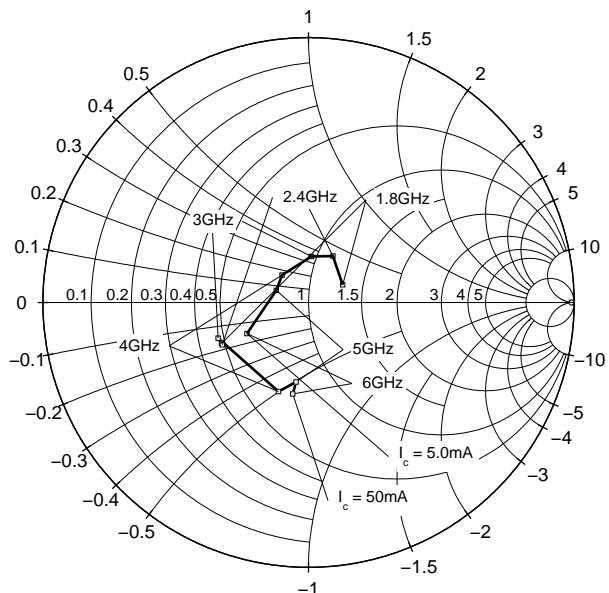
$V_{\text{CE}} = 1.5\text{V}, Z_{\text{S}} = Z_{\text{Sopt}}$



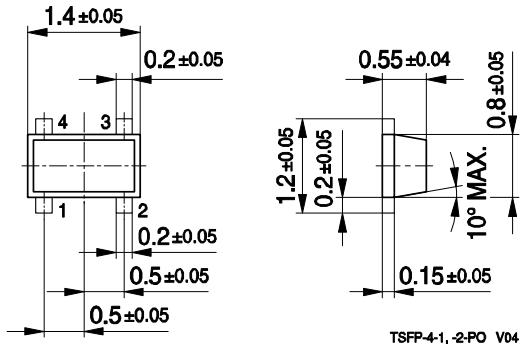
**Source impedance for min.**

noise figure vs. frequency

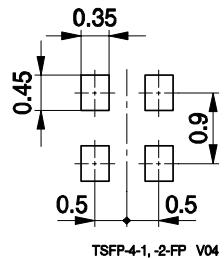
$$V_{CE} = 1.5V, I_C = 5.0\text{mA}/50.0\text{mA}$$



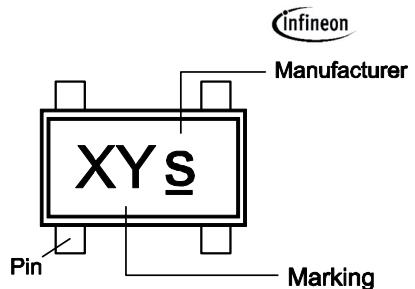
### Package Outline



### Foot Print

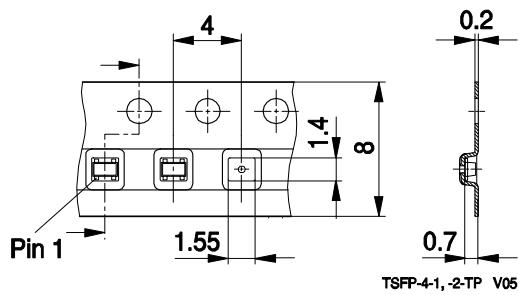


### Marking Layout (Example)



### Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
 Reel ø330 mm = 10.000 Pieces/Reel



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